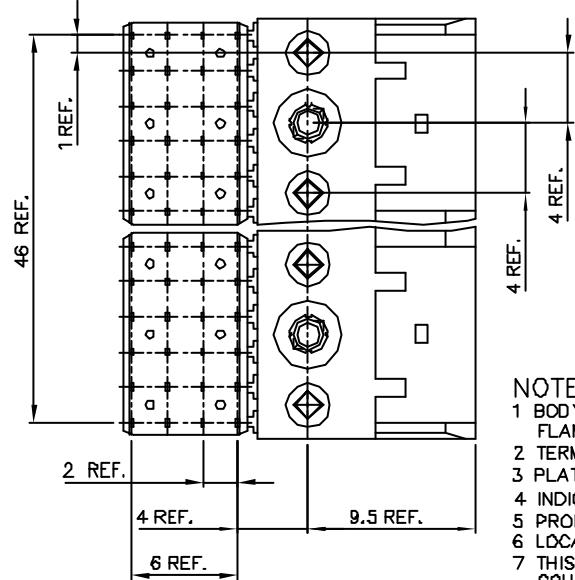
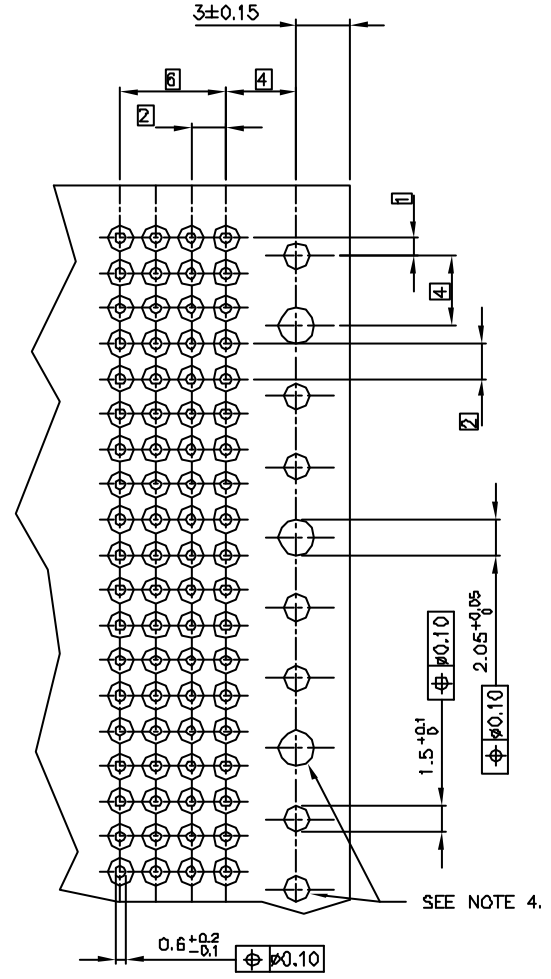
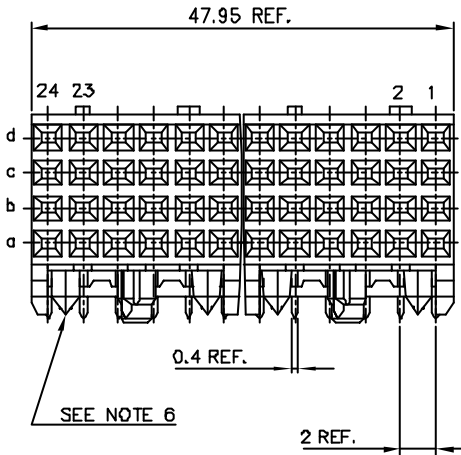
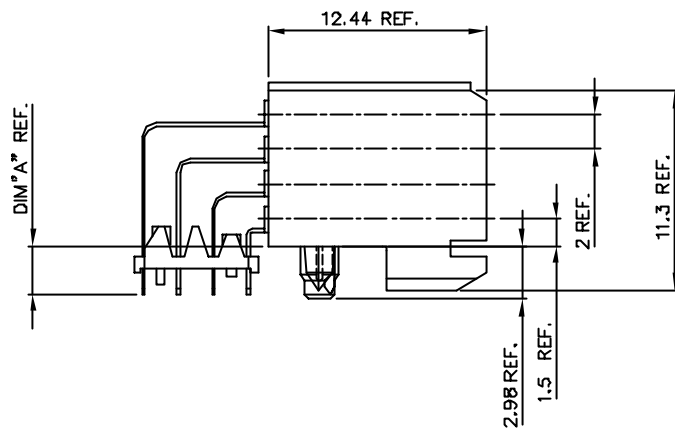
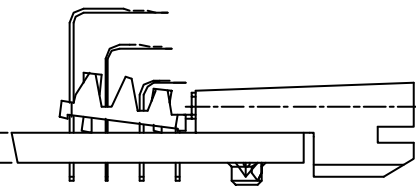


PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89037-X01/X01LF	1.6	2.73
89037-X11/X11LF	2.4	3.53



PRODUCT AFTER PC BOARD APPLICATION.



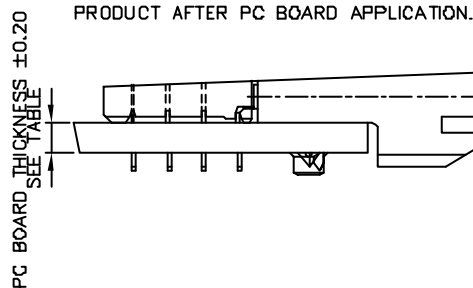
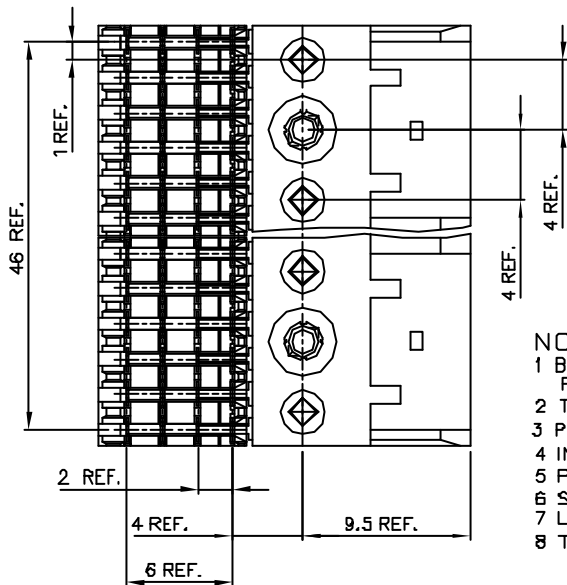
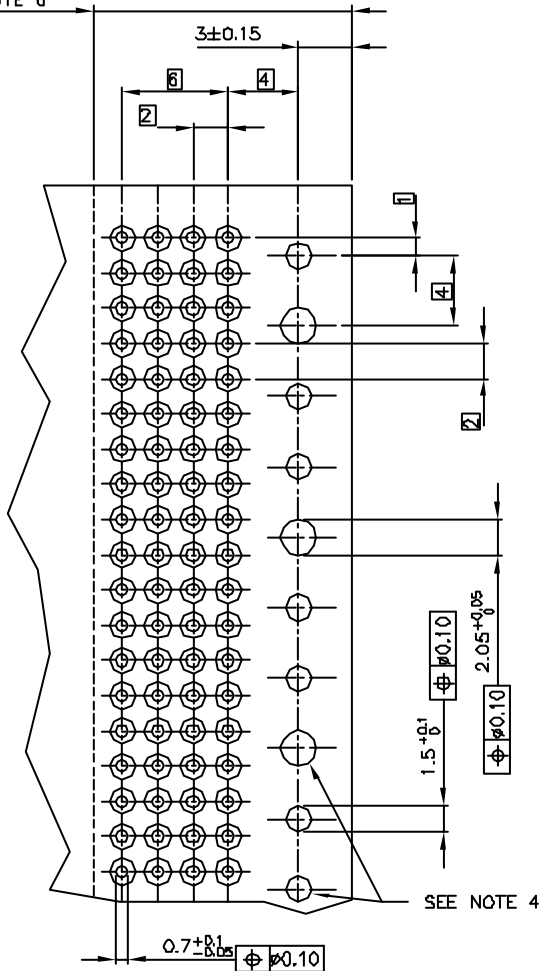
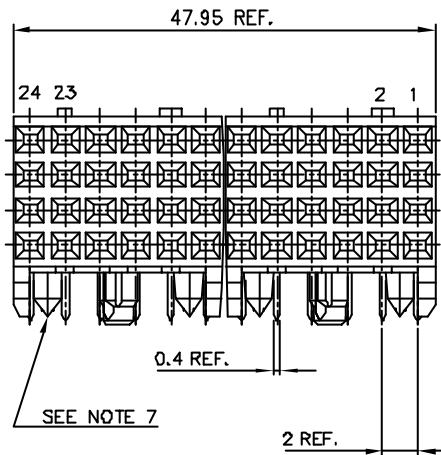
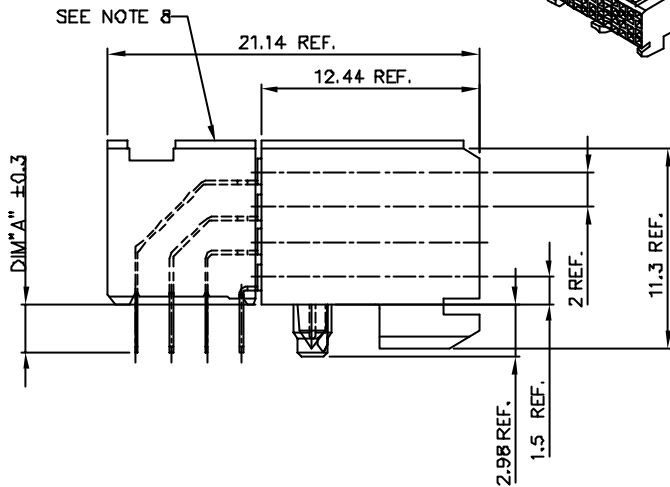
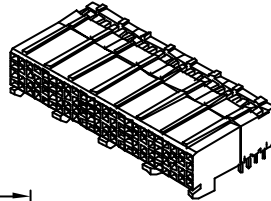
- NOTES:
- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS FLAME RETARDANT ACC. UL 94-V0
 - 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - 3 PLATING SOLDERTAILS 2-8 μ m SnPb 90-97 DR 2-8 μ m PURE Sn
 - 4 INDICATED HOLES ARE UNPLATED.
 - 5 PRODUCT MARKING: PARTNUMBER & BATCH ID.
 - 6 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
 - 7 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
 - 8 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
89037-1YZ/1YZLF	0.8 μ m GOLD	1.3 μ m Ni MIN.
89037-2YZ/2YZLF	2 μ m GOLD	1.3 μ m Ni MIN.
89037-3YZ/3YZLF	1.3 μ m GOLD	1.3 μ m Ni MIN.
89037-9YZ/9YZLF	0.8 μ m GXT	1.3 μ m Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER		ELECTRONICS	
itr	can no	dr	date	linear	projection	title	www.electronics.com
J	8904-0104	CU	041221			RA FEMALE SIGNAL	
D	H40-355	008	041007	angles		48 mm PRESS PEC	
F	V70769	008	070530	dr	H. Benknecht	product form	213
F	V81480	008	090827	eng	Pl. Baumkamp	size	213
S	V00078	008	000318	chr	S. Lee	dwg no	89037
N	V00047	008	000530	appl	J. W. Jans	sheet	1 of 2
sheet	revision	J	J				
index	sheet	1	2				

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PC BOARD VERSIONS		
PRODUCTNR:	PCB THICKNESS	DIM"A"
89037-X02/X02LF	1.6	2.73
89037-X12/X12LF	2.4	3.53



- NOTES:
- 1 BODY MAT'L: LIQUID CRYSTAL POLYMER 30% GLASS
FLAME RETARDANT ACC. UL 94-V0
 - 2 TERMINAL MATERIAL: PHOSPHOR BRONZE.
 - 3 PLATING SOLDER TAILS 2-8 µm SnPb 90-97 OR 2-8 µm PURE Sn
 - 4 INDICATED HOLES ARE UNPLATED.
 - 5 PRODUCT MARKING: PART NUMBER & BATCH ID.
 - 6 SET BACK FOR PRESS BLOCK.
 - 7 LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
 - 8 TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD
 - 9 THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-D08
 - 10 THE HOUSING WILL WITHSTAND EXPOSURE TO 260DEGREE PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION.

PRODUCT NR:	PLATING CONTACT AREA:	UNDERPLATING
B9037-1YZ/1YZLF	0.8 µm GOLD	1.3 µm Ni MIN.
B9037-2YZ/2YZLF	2 µm GOLD	1.3 µm Ni MIN.
B9037-3YZ/3YZLF	1.3 µm GOLD	1.3 µm Ni MIN.
B9037-9YZ/9YZLF	0.8 µm GXT	1.3 µm Ni MIN.

mat'l code		tolerances unless otherwise specified		CUSTOMER GDPY		ELECTRONICS	
itr	san no	dr	date	linear	projection	RA FEMALE SIGNAL	
				angles	1st angle	48 mm PRESS PCB	
		dr	0. de sn	970529	mm	product form	NETRAL (µm)
		eng	p. Schelt	970529	scale	89037	code
		chr	p. Schelt	970529	8:1		213
		appl.	Doc/mana	970529			sheet
sheet index	revision sheet						2 of